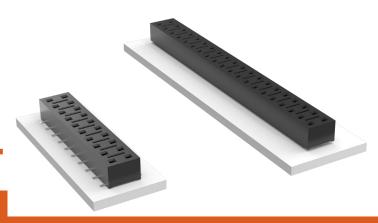


## **COST-EFFECTIVE** ELIABLE SOCK

(2.54 mm) .100" PITCH • HLE SERIES



#### HLE

**Board Mates:** TSW, MTSW, DW, EW, ZW, TLW, TSM, MTLW, HW

# HLE

NO. PINS PER ROW

02 thru 50

**PLATING** OPTION

Gold flash on

contact, Matte Tin on tail

= 10 μ" (0.25 μm)

Gold on contact, Matte Tin on tail

TAIL OPTION

**OTHER** OPTION

-BE

(Not available with –TE)

Bottom Entry

Leave blank for Surface Mount (Requires –BE for Bottom Entry)

-TE

= Through-hole Top Entry

-PE

= Through-hole Pass-through Entry (Requires –BE for Bottom Entry)

-A = Alignment Pin (4 positions min.) Metal or plastic at Samtec discretion (Not available with -TE, -PE & -LC)

-LC

= Locking Clip (2 positions min.) (Not available with -A) (Manual placement required)

**-K** = (6.50 mm) .256" DIA Polyimide Film Pick & Place Pad (3 positions min.) Not available with -TE or -PE tail option

-P

= Metal Pick & Place Pad (3 positions min.)

-TR

= Tape & Reel (29 positions max.)

-FR

= Full Reel Tape & Reel (must order max. quantity per reel; contact Samtec for quantity breaks)

#### **SPECIFICATIONS**

Insulator Material: Black Liquid Crystal Polymer Contact Material:

Contact Material:
BeCu
Plating:
Au or Sn over
50 μ" (1.27 μm) Ni
Operating Temp Range:
-55 °C to +125 °C
Current Rating (HLE/TSM):
4 1 A per pin

4.1 A per pin (2 pins powered) **Voltage Rating:** 400 VAC/566 VDC

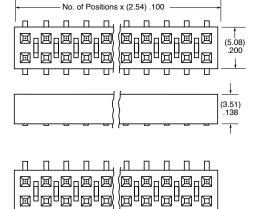
Insertion Depth:

(1.78 mm) .070" to (3.43 mm) .135", pass-through, or (2.59 mm) .102" min plus board thickness for bottom entry

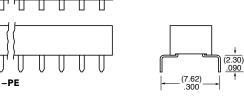
#### **PROCESSING**

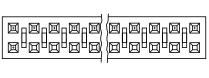
Lead-Free Solderable:

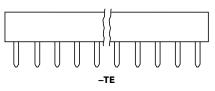
Yes SMT Lead Coplanarity: (0.10 mm) .004" max (02-20) (0.15 mm) .006" max (21-50)\* \*(.004" stencil solution may be available; contact ipg@samtec.com)



















### **ALSO AVAILABLE**

Other Platings

Some lengths, styles and options are non-standard, non-returnable.

F-224 (Rev 05SEP25)